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(54) **METHOD OF SOLDERING PRINTED BOARD, AND JET SOLDER VESSEL** COPYRIGHT: (C)2000,JPO

(57) Abstract:

PROBLEM TO BE SOLVED: To eliminate use of power from outside, prevent jet condition from changing by the adhesion of an oxide and prevent a bridge, an icicle, etc., from being generated.

SOLUTION: In this method, primary soldering is performed for a printed board by the roughened jet waves of a primary jet nozzle, and then soldering is performed again with the gentle jet waves of a secondary jet nozzle. In this case, meandering waves are made by letting fused solder flow out of the narrow outlet 9 of a jet 5, and applying the fused solder having flown out to the entry side to the wall face 12 of a trough 10, and making it interfere with the fused solder surging from behind. Performing the soldering of the printed board with the meandering waves will enable the soldering without a bridge or an icicle.

